

electronica Automotive Conference

November 9, 2026, ICM – International Congress Center Messe München

Time	Opening and AI in Automotive					
09:00	Conference Opening by Caroline Pannier, Messe München and Peter Gresch, OptE GP Consulting					
09:10	Marcus Hafkemeyer, CEO, Carizon: TBA					
09:35	Torsten Gollewski, Executive Vice President Corporate R&D Innovation & Technology, ZF Group: Transformation of Software Development with AI					
10:00	Dr. Joachim Fetzer, President Europe, CEO, FMC3 Robotics: Humanoid Robots – one size fits all?					
10:25	Paolo Denti, CEO, Oversonic Robotics: Humanoids at work: what it takes to put cognitive robots into automotive production – Edge compute, functional safety and industrial reliability: lessons from industrial deployments of humanoid robots in industrial manufacturing process					
10:50	Coffee break					
11:20	Dr. Rupert Stützle, General Manager Manufacturing & Mobility EMEA, Microsoft: How to build the Agentic AI platform for R&D that ensures impact and cost control					
11:40	Taylor Young, CSO, CoLab Software: How do we go faster, without sacrificing quality and cost?					
12:00	Dr. Thomas Kaufmann, EVP & COO Automotive, Infineon Technologies: Winning in a fragmenting automotive world – Turning geopolitical complexity into competitiveness through multi-site manufacturing, multi-sourcing, and regional go-to-market strategies					
12:20	Interview Session: Kraft statt Krise (Short presentation, followed by an interview and audience discussion) Harald Hamprecht, author & advisor					
12:45	Lunch break					
Chair	Chair Discussion: Resilience in the Supply Chain Ole Gerkenmeyer, Nexperia		Chair Discussion: Challenges and Trends in Electronics and Lighting R&D Robert Isele, Inova		Chair Discussion: Electrification Dr. Wolfgang Bochtler, JPW	
13:45	Risks and Opportunities in the Electronics Component	Ole Gerkenmeyer, CSO, Nexperia	XiM27 Concept car – defining next level smart cabin & interior lighting experience	Christophe Pincemin, Executive Director Smart Surfaces & Lighting, Yanfeng	Three decades of SiC innovation leading to 200 mm production and full vertical integration	Manuel Gärtner, Director Wide Bandgap & Electrification, STMicroelectronics
14:10	Wheels, Legs and Chips: Mapping the Physical AI Semiconductor Opportunity	Claire Troadec, Global Semiconductors Director, Yole Group	Static and Dynamic Headlight Leveling based on MEMS accelerometer and Software Algorithm	Tommi Vilenius, Senior Manager, Business Development, Automotive, Murata Electronics	Flexible and Printed Electronics for Automotive	Dr. Klaus Hecker, Managing Director OE-A, VDMA
14:35	Closed Loop Control Development with Functional Twins	Torsten Hermann, Senior Expert Virtualization, Aumovio	When Surfaces Come Alive: Next-Level Automotive Interior Lighting	Stephan Eicher, Director of Product Marketing, ams OSRAM	More than just a connection: Smart FPCs simplify, secure and optimise battery module wiring.	Markus Voeltz, Business Development Director Europe, CEE PCB
15:00	High-Performance Graphic Display Controller – Architectures for Next-Generation Cockpits	Mark Müller, Senior Marketing Manager Automotive, Socionext Europe	Powering the Electric Era with Secure Data, Trusted Devices, and Intelligent Protection	Wolfgang Steinbauer, SVP Head of Crypto and Security, NXP Semiconductors	Efficiency at the Edge: AI as the Engine of Sustainable Electrification	Nicisor Penisoara, AI IP and Solutions Lead, NXP Semiconductors
15:20	Coffee break					

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	CTO Session
15:40	Stephan Berlitz, VP Light, Audi AG: Audi.Digital.Light – Technology trends in premium exterior and interior lighting
15:55	Norbert Bauer, CTO, JoysonPreh: How interiors create differentiation
16:10	Jochen Weihgold, CTO, Neusoft Technology Solutions: From Technology-Defined to Scenario-Defined: Rethinking Automotive User Experience with AI – Insights from China's Rapid AI Deployment in Mobility
16:25	Dr. Flavio Friesen, CTO, Holon: New Mobility Concepts through Automated Transportation – The HOLON urban
16:40	Dr. Grzegorz Ombach, SVP, Airbus: When AI Enters the Physical World: The Rise of Physical and Agentic AI – Lessons from aerospace on scaling intelligent products, machines and operations
	CTO Roundtable: Is AI in Automotive Industry just a Hype? What are the opportunities, where do you see risks?
17:00	Norbert Bauer, JoysonPreh; Flavio Friesen, Holon; Dr. Grzegorz Ombach, Airbus; Stephan Berlitz, Audi; Jochen Weihgold, Neusoft Technology Solutions
17:30	End of Conference

Program as per October 22, 2026

Information and ticket registration under electronica.de/automotiveconference



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